

1

2

3

4

5

6

7

8

9

10

11

符合"DLK环境管理物质技术标准"

符合USB3.0协会规范标准"

②

DLK LOGO

DLK

POS 5

POS 9

2

1

3

4

11.70±0.20

12.6±0.38

18.3±0.38

2.60

2.7±0.1

10.30±0.25

2.80

12.00±0.3

10.30

2.70

2.00

2.00

8.50

1.75

2.50

4.60

11.70

2.20

1.00

0.70±0.05

0.90±0.05

PCB LAYOUT(TOP VIEW T=1.60)

工程变更通知单
ECN(DCN) NO.

版本
REV

日期
DATE

说明
DESCRIPTION

变更
CHANGE

核准
APPRO.

—

X0

20160519

NEW RELEASE

—

—

—

X1

20160715

增加HF标示

王永辉

U3B22 D-09 * ** Y N2 0 HF

① ② ③ ④ ⑤ ⑥ ⑦

① PRODUCTION CODE (产品编码):
U3B22: USB 3.0 BF DIP 12.6H

② CHARACTER (特征):
D:DIP TYPE

③ POSITION (位数):
09: 9PIN

④ COLOR OF HOUSING(本体颜色):
→ L:BLUE
→ B:BLACK

⑤ PLATING OF CONTACT(端子电镀):
→ M1 : Au 1U" AND MATTE TIN 100U" PLATED
→ M4 : Au 15U" AND MATTE TIN 100U" PLATED
→ M5 : Au 30U" AND MATTE TIN 100U" PLATED

⑥ PACKAGE(包装):
Y :TRAY PACKAGE

⑦ PLATING OF SHELL(铁壳电镀):
N2 :Ni plated

A区:打镍底50u"
B区:先镀镍50u"再单面刷金1u"
C区:先镀镍50u"再镀锡100u"

1.40

B区

端子镀金测点

C区

B厚金区, 先镀Ni50u"再
单面刷金测点Au 15u"

2.40

5.00

A区:打镍底50u"
B区:先镀镍50u"再单面刷金1u"
C区:先镀镍50u"再镀锡100u"

2.00

B区

端子镀金测点

C区

B厚金区, 先镀Ni50u"再
单面刷金测点Au 15u"

4.00

5.00

C2680(C5191)/0.25T

Ni 99.99%(Thickness 50u"min)

Sn 99.99%(Thickness 100u"min)

CONTACT

C2680/0.3T

Ni 99.99%(Thickness 40u"min)

SHELL

德力康电子科技有限公司
DLK DELIKANG ELECTRONICS TECHNOLOGY CO.,LTD

名称
TITLE

档案名称
FILE NAME.

DRAWING

UNIT:

mm

SCALE

1:1

SHEET: 1 of 1

USB 3.0 BF DIP 12.6H

C-U3B22-00-HF

料号
PART NO.

U3B22D-09***YN20HF

王永辉

CHECKED

APPROVED

GENERAL TOLERANCE
UNLESS OTHERWISE NOTED

Angle ±2°

X. ±0.38

.X ±0.30

.XX ±0.25

.XXX ±0.15

A4

4

COVER

1

PBT

UL94V-0

3

CONTACT

9

C2680/C5191

Au PLATED

2

SHELL

1

C2680

Ni PLATED

1

HOUSING

1

PBT

UL94V-0

NO.

ITEM

Q'TY

DESCRIPTION

FINISH

1

2

3

4

5

6

7

8

9

10

11